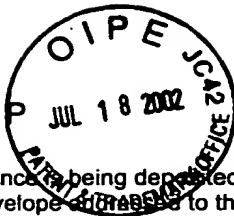


Docket No.: GR 98 P 1075 P



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Date: July 12, 2002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Manfred Fries et al.
Applic. No. : 09/627,181
Filed : July 27, 2000
Title : Chip Smart Card Module for Biometric Sensors
Art Unit : 2721

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INFORMATION DISCLOSURE STATEMENT

Hon. Commissioner of Patents and Trademarks,
Washington, D.C. 20231

Sir:

In accordance with 37 C.F.R. 1.98 copies of the following patents and/or publications are submitted herewith:

Japanese Patent Abstract JP 1 152 590 (Watanabe), dated June 15, 1989;

Japanese Patent Abstract JP 9 171 547 (Yagi), dated June 30, 1997;

Korean office Action dated May 29, 2002.

In accordance with 37 C.F.R. 1.97(e) the undersigned herewith states that each item of information contained in the information disclosure statement was first cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the information disclosure statement.

If no translation of pertinent portions of any foreign language patents or publications mentioned above is included with the aforementioned copies of those applications,

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patents and/or publications, it is because no existing translation is readily available to the applicant.

Respectfully submitted,



For Applicants

Mark P. Weichselbaum
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Date: July 12, 2002

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